

SOT791-1

plastic low profile quad flat package; 64 leads; body 14 x 14 x 1.4 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	LQFP64
Package type industry code	LQFP64
Package style descriptive code	LQFP (low profile quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	136E18
JEDEC package outline code	MS-026
JEITA package outline code	ED-7311EC
Mounting method type	S (surface mount)
Issue date	22-10-2002

Table 1. Package summary

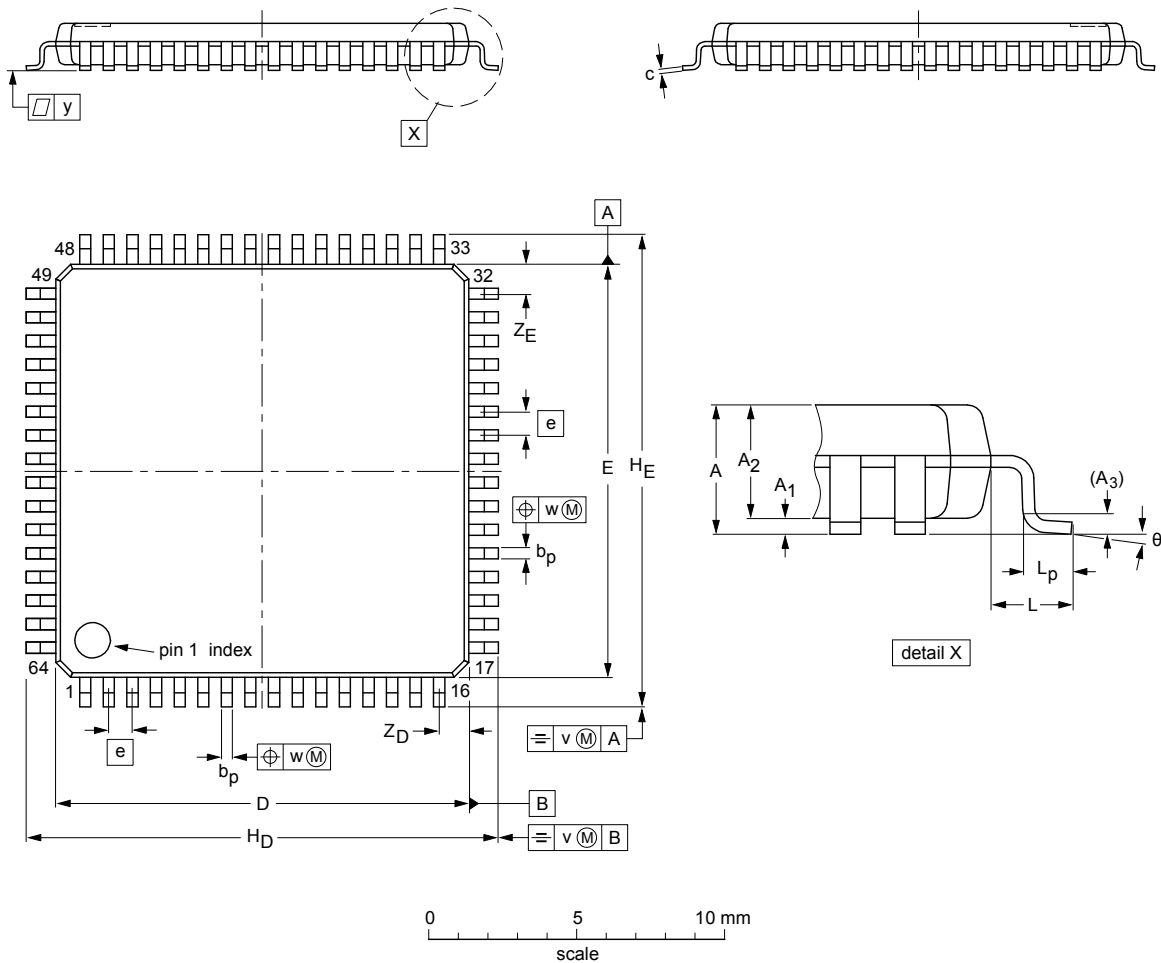
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	13.9	-	14	14.1	mm
E	package width	13.9	-	14	14.1	mm
A	seated height	[tbd]	-	1.6	1.6	mm
A ₂	package height	1.35	-	1.4	1.45	mm
n ₂	actual quantity of termination	-	-	64	-	



2. Package outline

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	1.6	0.15 0.05	1.45 1.35	0.25	0.45 0.30	0.20 0.09	14.1 13.9	14.1 13.9	0.8	16.15 15.85	16.15 15.85	1	0.75 0.45	0.2	0.2	0.1	1.2 0.8	1.2 0.8	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT791-1	136E18	MS-026	ED-7311EC		02-10-22

Fig. 1. Package outline LQFP64 (SOT791-1)

3. Soldering

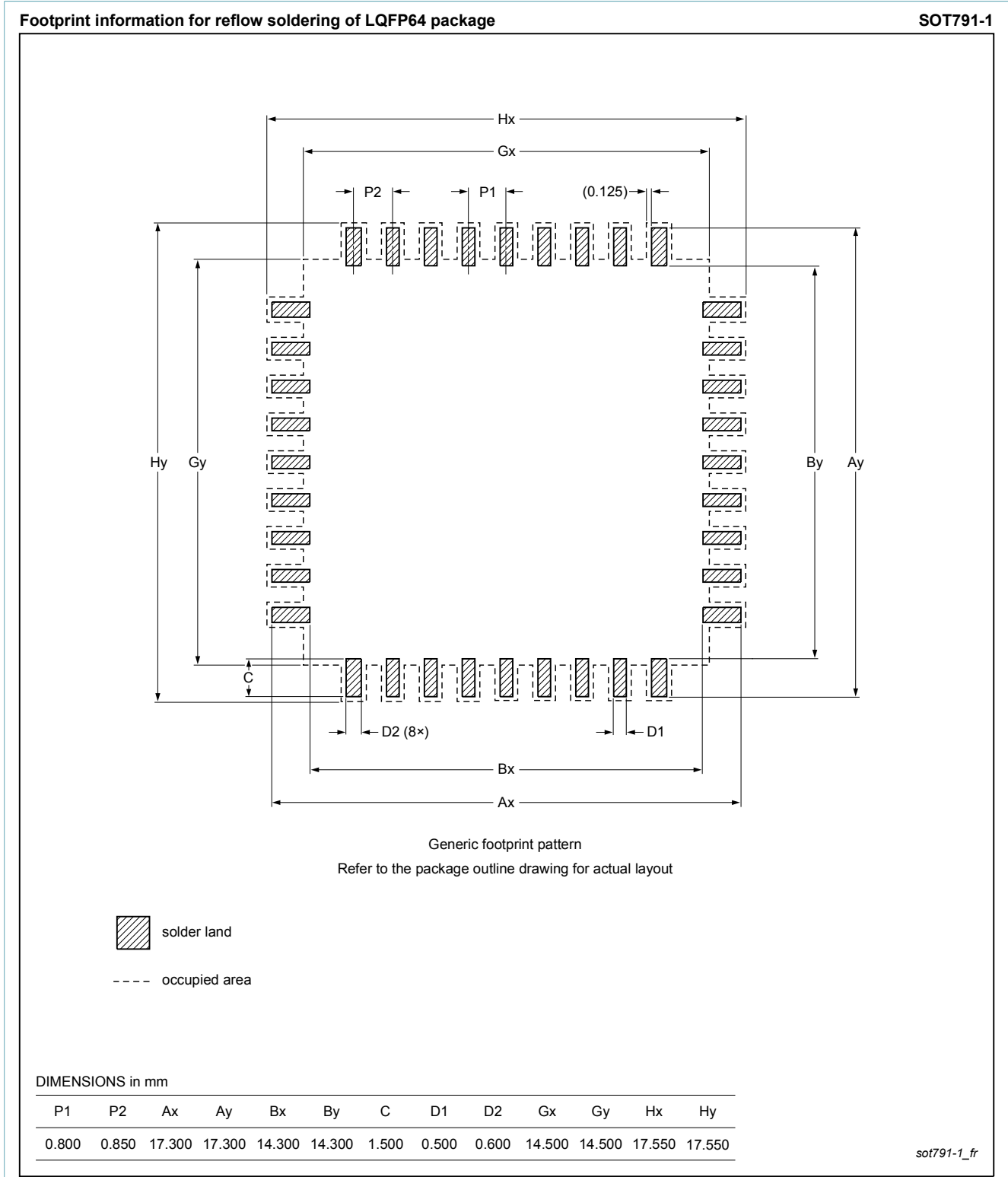


Fig. 2. Reflow soldering footprint for LQFP64 (SOT791-1)

4. Legal information

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